

**Table 1. Electrical Performance**

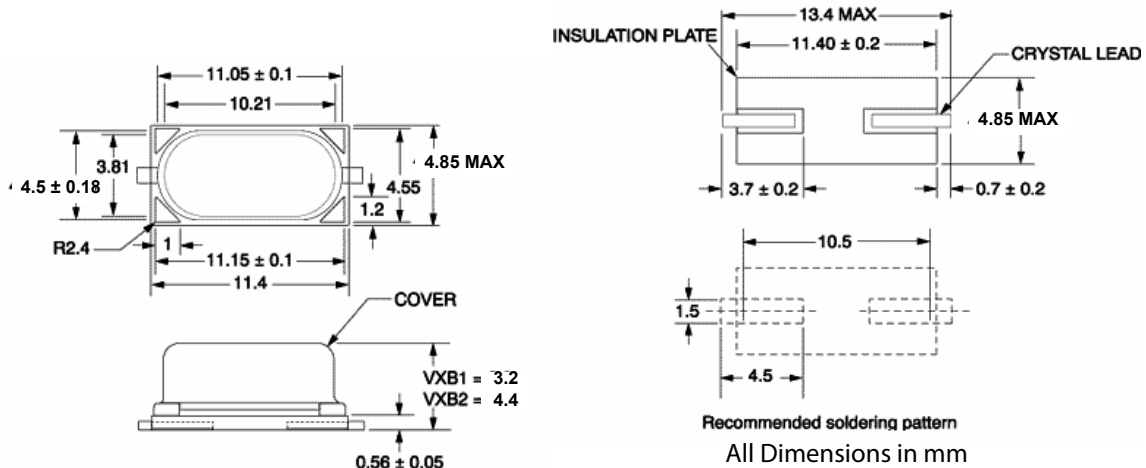
Parameter	Symbol	Min.	Typ	Max	Units
Nominal Frequency	F <sub>NOM</sub>	3.500		75.000	MHz
Mode		Fundamental, 3rd Overtone			
Operating Temperature Range	T <sub>OP</sub>	0/70, -10/70, -20/70, -40/85			°C
Stability Over T <sub>OP</sub> <sup>1</sup>	F <sub>STAB</sub>	±10		±100	ppm
Frequency Tolerance <sup>2</sup>	F <sub>TOL</sub>		±10		ppm
Load Capacitance	C <sub>L</sub>	6		32	pF
Shunt Capacitance	C <sub>o</sub>			5	pF
Drive Level			10	100	uW
Aging / 1st year (at 25 °C)	F <sub>AGE</sub>			±5	ppm
Insulation Resistance		500			MOhm
Storage Temperature	T <sub>STO</sub>	-40		90	°C
Equivalent Series Resistance					
Crystal Frequency	ESR				Ohm
3.500MHz-4.000MHz				140	
4.001MHz-5.000MHz				120	
5.001MHz-6.000MHz				80	
6.001MHz-7.000MHz				70	
7.001MHz-9.000MHz				45	
9.001MHz-13.000MHz				40	
13.001MHz-16.000MHz				35	
16.001MHz-20.000MHz				30	
20.001MHz-30.000MHz, Fundamental				25	
24.001MHz-32.000MHz, 3rd Overtone				120	
32.000MHz-80.000MHz, 3rd Overtone				80	

Notes:

1. Referenced to the Frequency at 25 °C.
2. Frequency measured at 25 °C ± 3 °C.

Product is compliant to RoHS directive and fully compatible with lead free assembly.

## Package Drawing



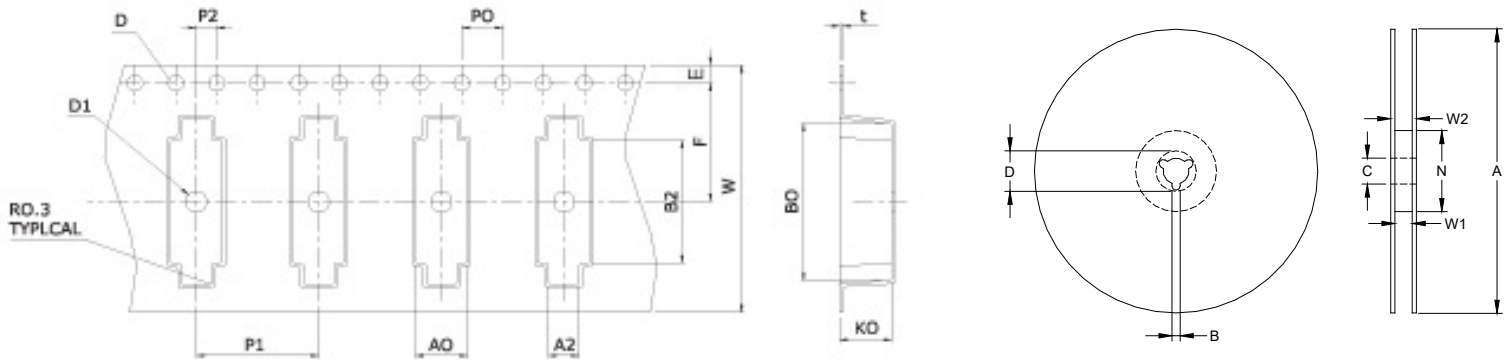
# Tape & Reel

**Table 7a. Tape and Reel Dimensions (mm)**

Tape														
Package	A0	A2	B0	B2	D	D1	E	F	K0	P0	P1	P2	t	W
VXB1	5.1	3.0	16.1	11.9	1.55	1.6	1.75	11.5	3.4	4.0	12.0	2.0	0.4	24.0
VXB2	5.1	3.0	16.1	11.9	1.5	2.0	1.75	11.5	4.3	4.0	12.0	2.0	0.4	24.0

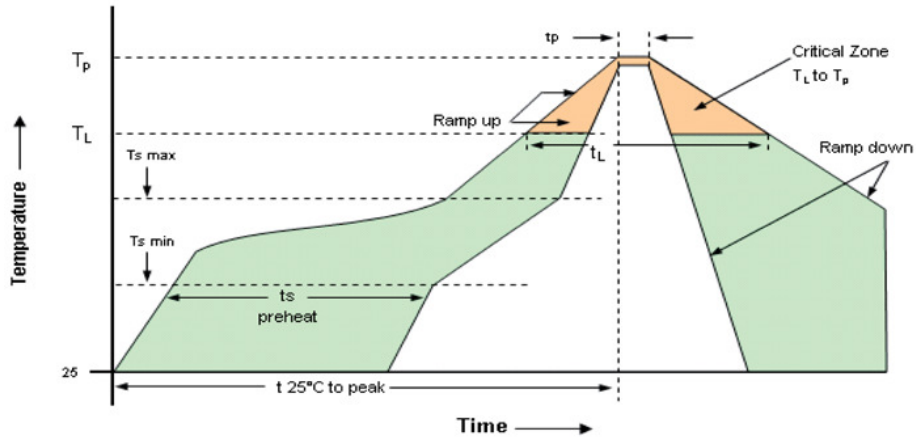
**Table 7b. Tape and Reel Dimensions (mm)**

Reel							
Package	A	A	C	D	W1	W2	N
VXB1	330	1.5	13	20.2	24.4	26.4	100
VXB2	330	2.0	13	21.0	24.4	26.4	80



## Reliability & IR Compliance

**Solderprofile:**



**Table 2: Reflow Profile**

Parameter	Symbol	Value
PreHeat Time Ts-min Ts-max	$t_s$	60 sec Min, 260 sec Max 150°C 200°C
Ramp Up	$R_{UP}$	3 °C/sec Max
Time Above 217 °C	$t_L$	60 sec Min, 150 sec Max
Time To Peak Temperature	$T_{AMB-P}$	480 sec Max
Time at 260 °C	$t_p$	30 sec Max
Ramp Down	$R_{DN}$	6 °C/sec Max

## Ordering Information

### VXBX - XXX - XX- xxMxxxxxxx

**Product**

VXB1: 3.2mm tall  
VXB2: 4.4mm tall

**Mode**

1: Fundamental  
3: 3rd Overtone

**Temp Stability**

D: 15ppm  
E: 20ppm  
F: 25ppm  
G: 30ppm  
H: 35ppm  
I: 40ppm  
J: 45ppm  
K: 50ppm  
S: 100ppm

**Frequency in MHz**

**Load Capacitance**

00: Series Resonance  
06-32pF

**Operating Temperature**

E: -40 to 85 °C  
J: -20 to 70 °C  
W: -10 to 70 °C  
T: 0 to 70 °C

*\*Note: not all combination of options are available.  
Other specifications may be available upon request.*

*15ppm stability not available for -40 to 85°C*

## Revision History

Revision Date	Approved	Description
August 30, 2016	RC	Initial datasheet for factory approval and release to customer.
August 10, 2018	FB	Update logo and contact information



**Microsemi Headquarters**  
One Enterprise, Aliso Viejo, CA 92656 USA  
Within the USA: +1 (800) 713-4113  
Outside the USA: +1 (949) 380-6100  
Sales: +1 (949) 380-6136  
Fax: +1 (949) 215-4996  
email: sales.support@microsemi.com  
www.microsemi.com

Microsemi, a wholly owned subsidiary of Microchip Technology Inc. (Nasdaq: MCHP), offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions; security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Learn more at [www.microsemi.com](http://www.microsemi.com).

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the Buyer's responsibility to independently determine suitability of any products and to test and verify the same. The information provided by Microsemi hereunder is provided "as is, where is" and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information itself or anything described by such information. Information provided in this document is proprietary to Microsemi, and Microsemi reserves the right to make any changes to the information in this document or to any products and services at any time without notice.

©2018 Microsemi, a wholly owned subsidiary of Microchip Technology Inc. All rights reserved. Microsemi and the Microsemi logo are registered trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.

# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Vectron:](#)

[VXB1-1B4-25M0000000](#) [VXB2-1B1-12M000](#)